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(12) **United States Design Patent**  
**Alfredsson et al.**

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(45) **Date of Patent:** **\*\* Apr. 6, 2021**

(54) **ELECTRONIC DEVICE HOUSING**

**DESCRIPTION**

- (71) Applicant: **ABB Schweiz AG**, Baden (CH)
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- (73) Assignee: **ABB Schweiz AG**, Baden (CH)
- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/687,631**
- (22) Filed: **Apr. 15, 2019**
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  - Oct. 15, 2018 (EM) ..... 005798378
  - Apr. 5, 2019 (EM) ..... 006370771
- (51) **LOC (13) Cl.** ..... **13-03**
- (52) **U.S. Cl.**  
USPC ..... **D13/184**; D13/110; D13/123
- (58) **Field of Classification Search**  
USPC ..... D13/110, 123, 158, 162, 184, 199;  
D14/301, 439

(Continued)

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

- D348,269 S \* 6/1994 Chong ..... D13/184
  - D373,362 S \* 9/1996 Kuroiwa ..... D13/184
- (Continued)

**OTHER PUBLICATIONS**

ABB Launches new microgrid system to boost use of renewables;  
Oct. 10, 2016; 1 pg.; <https://www.windpowerengineering.com/abb-launches-new-microgrid-system-boost-use-renewables/>.\*

(Continued)

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(57) **CLAIM**

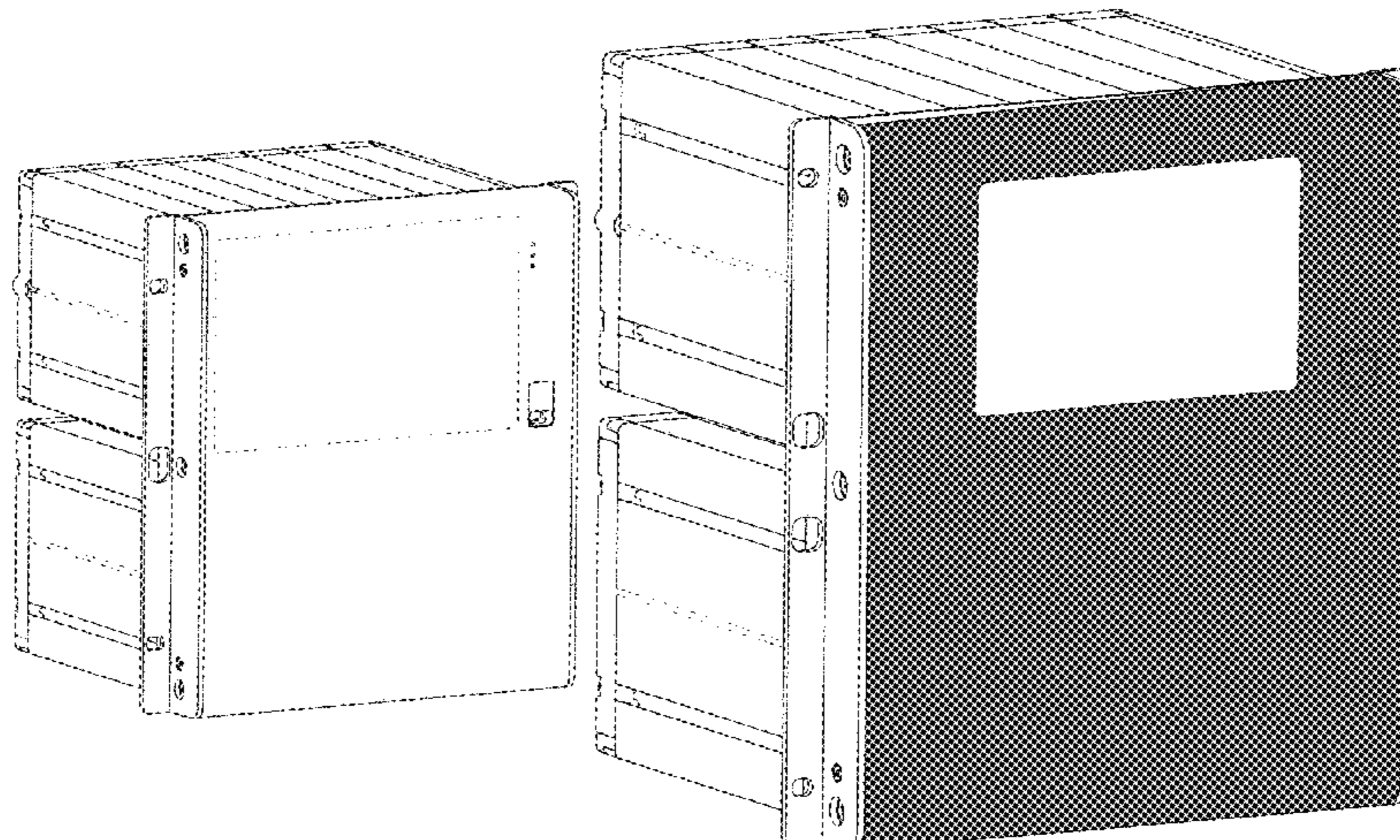
The ornamental design for a electronic device housing, as shown and described.

FIG. 1 is a top, front isometric view of a first embodiment of a electronic device housing in accordance with-the new design;  
FIG. 2 is a left side elevational view of the embodiment shown in FIG. 1;  
FIG. 3 is a right side elevational view of the embodiment shown in FIG. 1;  
FIG. 4 is a front elevational view of the embodiment shown in FIG. 1;  
FIG. 5 is a rear elevational view of the embodiment shown in FIG. 1;  
FIG. 6 is a top plan view of the embodiment shown in FIG. 1;  
FIG. 7 is a bottom plan view of the embodiment shown in FIG. 1;  
FIG. 8 is a top, front isometric view of a second embodiment of the electronic device housing in accordance with the new design;  
FIG. 9 is a left side elevational view of the embodiment shown in FIG. 8;  
FIG. 10 is a right side elevational view of the embodiment shown in FIG. 8;  
FIG. 11 is a front elevational view of the embodiment shown in FIG. 8;  
FIG. 12 is a rear elevational view of the embodiment shown in FIG. 8;  
FIG. 13 is a top plan view of the embodiment shown in FIG. 8; and,  
FIG. 14 is a bottom plan view of the embodiment shown in FIG. 8.

The broken line portions of the figure drawings are included to show unclaimed subject matter only and form no part of the claimed design.

The dash-dot broken lines define the bounds of the claimed design and form no part thereof.

**1 Claim, 14 Drawing Sheets**



(58) **Field of Classification Search**

CPC ..... G05B 9/02; G05B 19/05; G05B 19/054;  
 G05B 19/056; G06F 1/182; G06F 1/183;  
 G06F 1/26; H05K 7/1462; H05K 7/1467;  
 H05K 7/1474; H05K 7/1432; H02B 1/26;  
 H02B 1/30; H02B 1/305

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D424,529	S	*	5/2000	Raspotnig	.....	D13/184
D437,586	S	*	2/2001	Sonntag	.....	D13/184
D493,771	S	*	8/2004	Pagella	.....	D13/110
D506,977	S	*	7/2005	Lee	.....	D13/110
D643,376	S	*	8/2011	Naumann	.....	D13/160
D702,198	S	*	4/2014	Gretz	.....	D13/184
D707,187	S	*	6/2014	Mauchle	.....	D13/162
D719,105	S	*	12/2014	Shin	.....	D13/159
D762,495	S	*	8/2016	Tanaka	.....	D10/50
D772,171	S	*	11/2016	Ohmori	.....	D13/158
D823,798	S	*	7/2018	Gleave	.....	D13/110
D860,957	S	*	9/2019	Gao	.....	D13/184

D867,304	S	*	11/2019	Tsurumi	.....	D13/159
10,547,161	B1	*	1/2020	Lin	.....	H02B 1/305
D877,701	S	*	3/2020	Byrne	.....	D13/139.4
10,707,768	B2	*	7/2020	Voegeli	.....	H05K 7/20009
2004/0008492	A1	*	1/2004	Kato	.....	G05B 19/0421 361/715
2011/0222244	A1	*	9/2011	Takashiro	.....	H05K 7/1432 361/704
2011/0242770	A1	*	10/2011	Yamanaka	.....	H05K 7/1432 361/728
2013/0016481	A1	*	1/2013	Takahashi	.....	H05K 7/20418 361/724
2019/0165687	A1	*	5/2019	Yamazawa	.....	B32B 15/082
2020/0059163	A1	*	2/2020	Koshii	.....	H02M 7/003

OTHER PUBLICATIONS

Rolls-Royce and ABB partner to develop micogrid solution for business; Apr. 2, 2019; 1 pg. ; <https://www.edie.net/news/8/Rolls-Royce-and-ABB-partner-to-develop-microgrid-solution-for-business/>.\*

\* cited by examiner

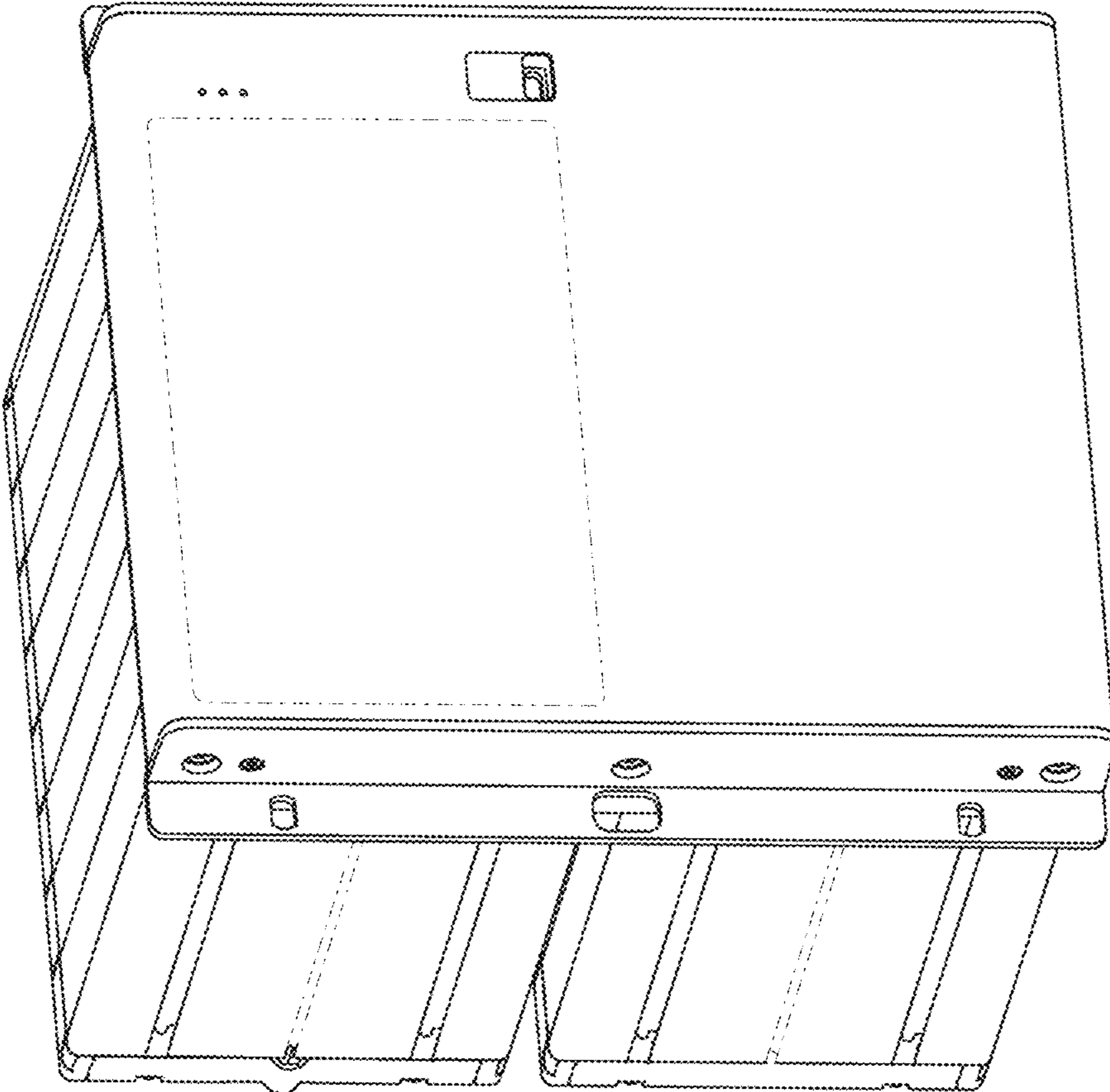


FIG. 1

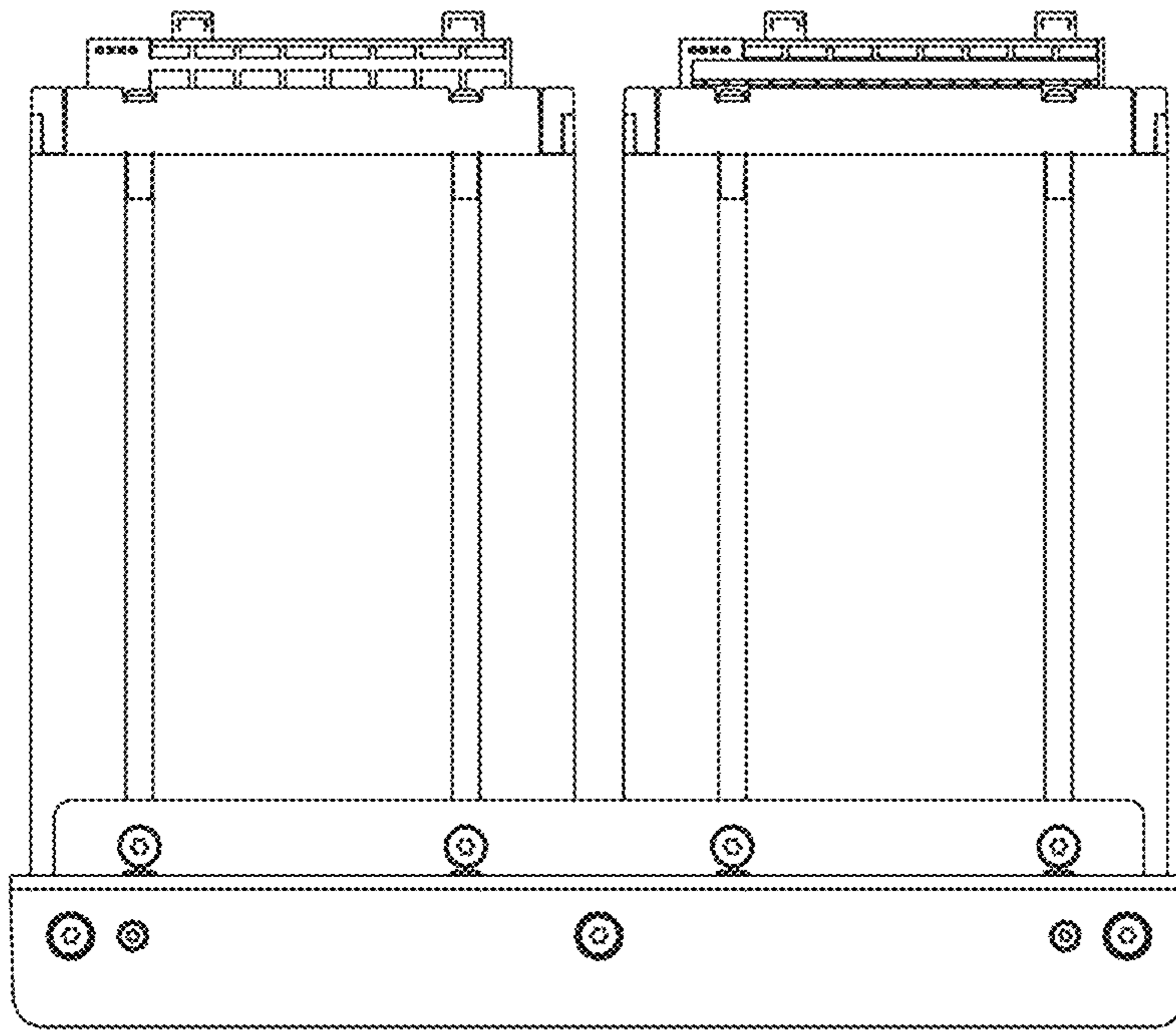


FIG. 2



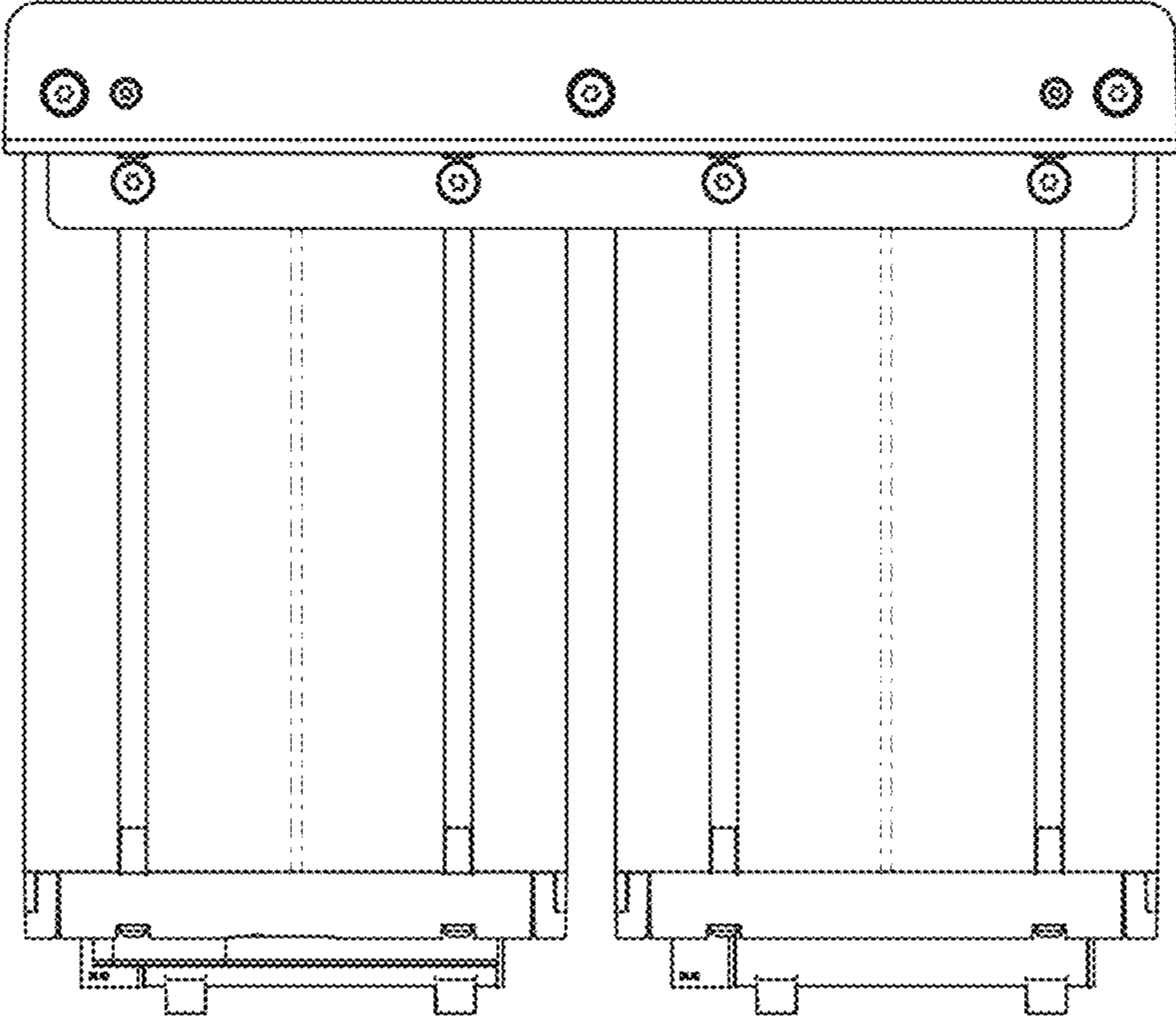


FIG. 3

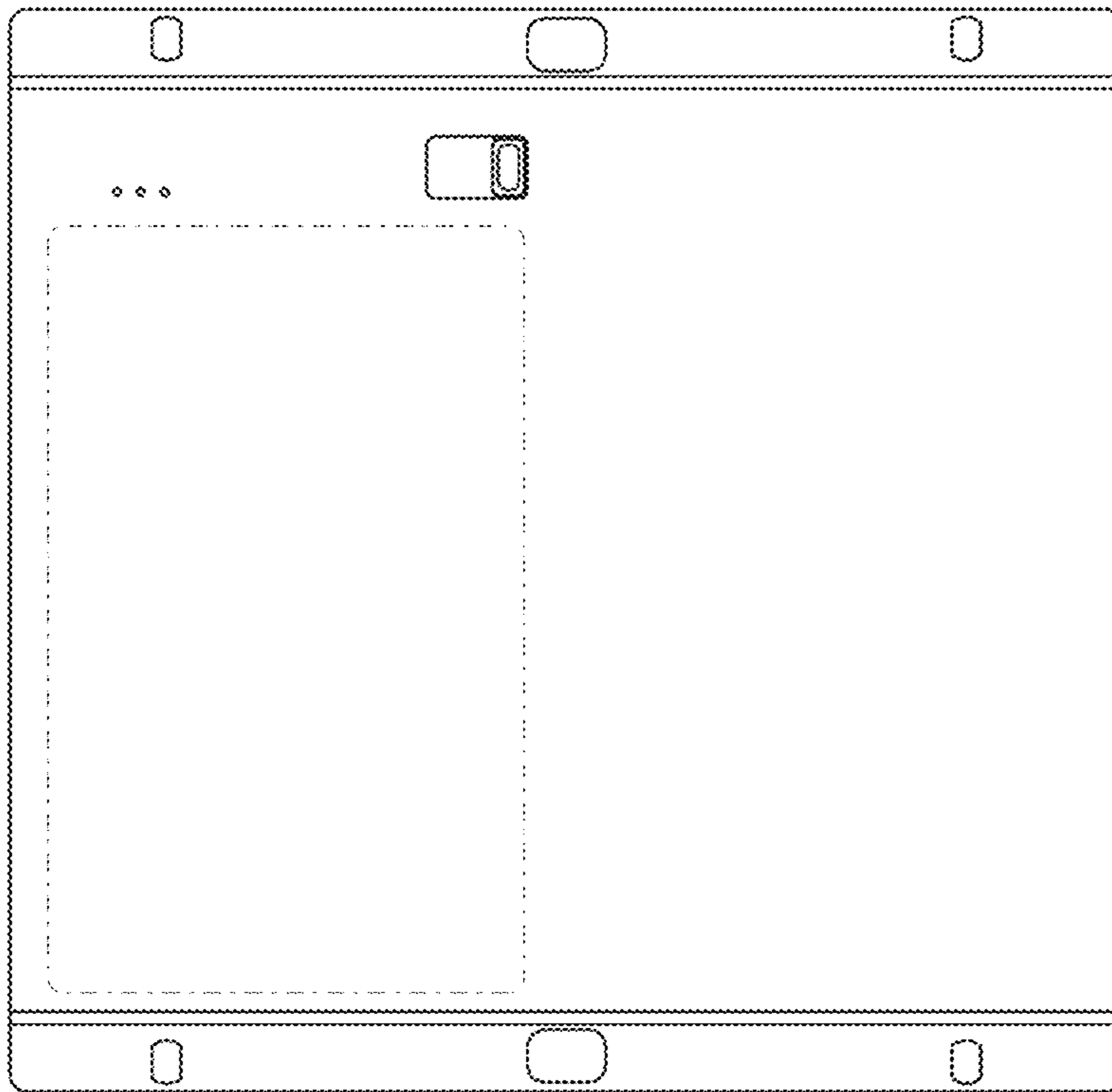


FIG. 4

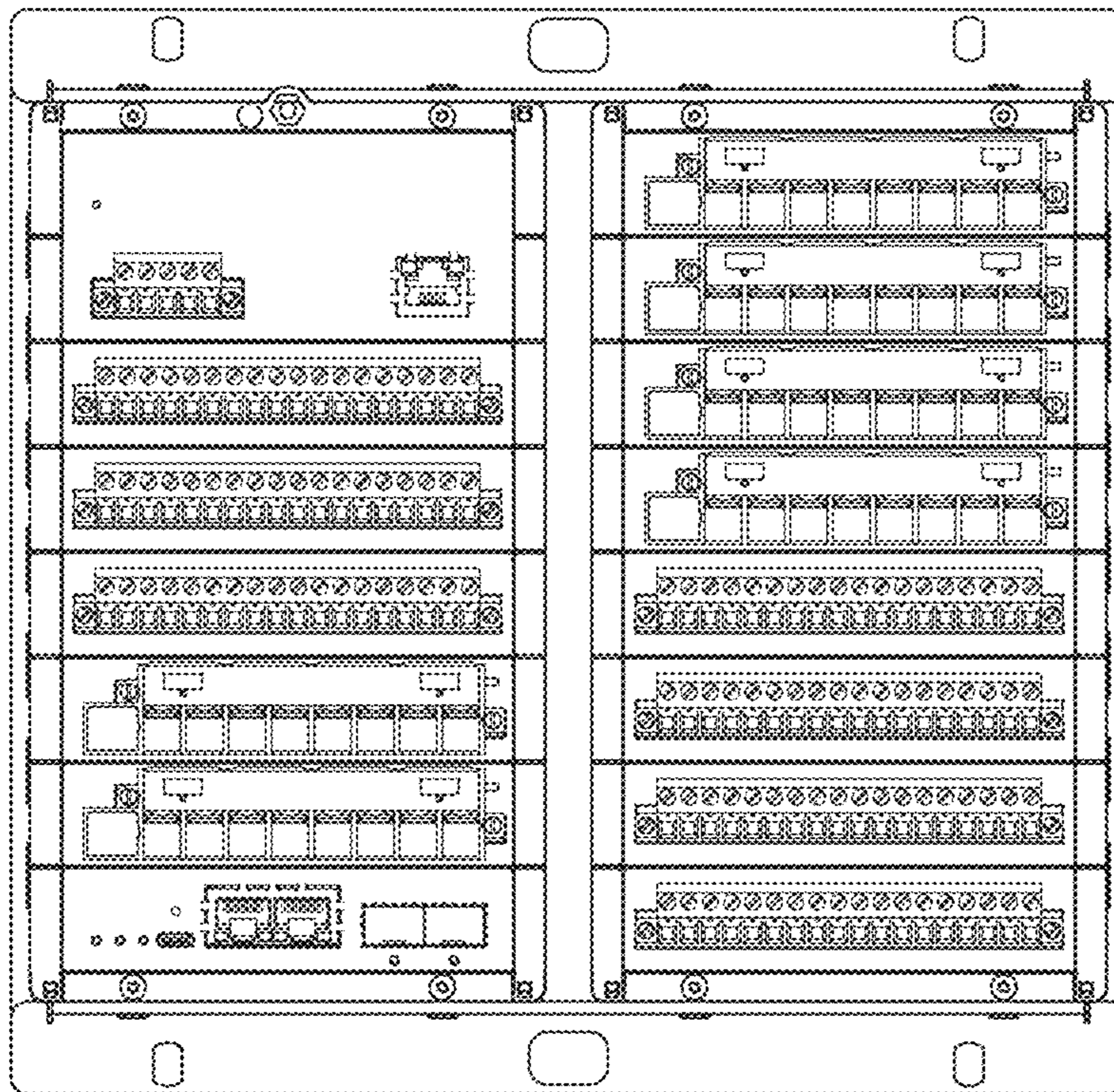


FIG. 5

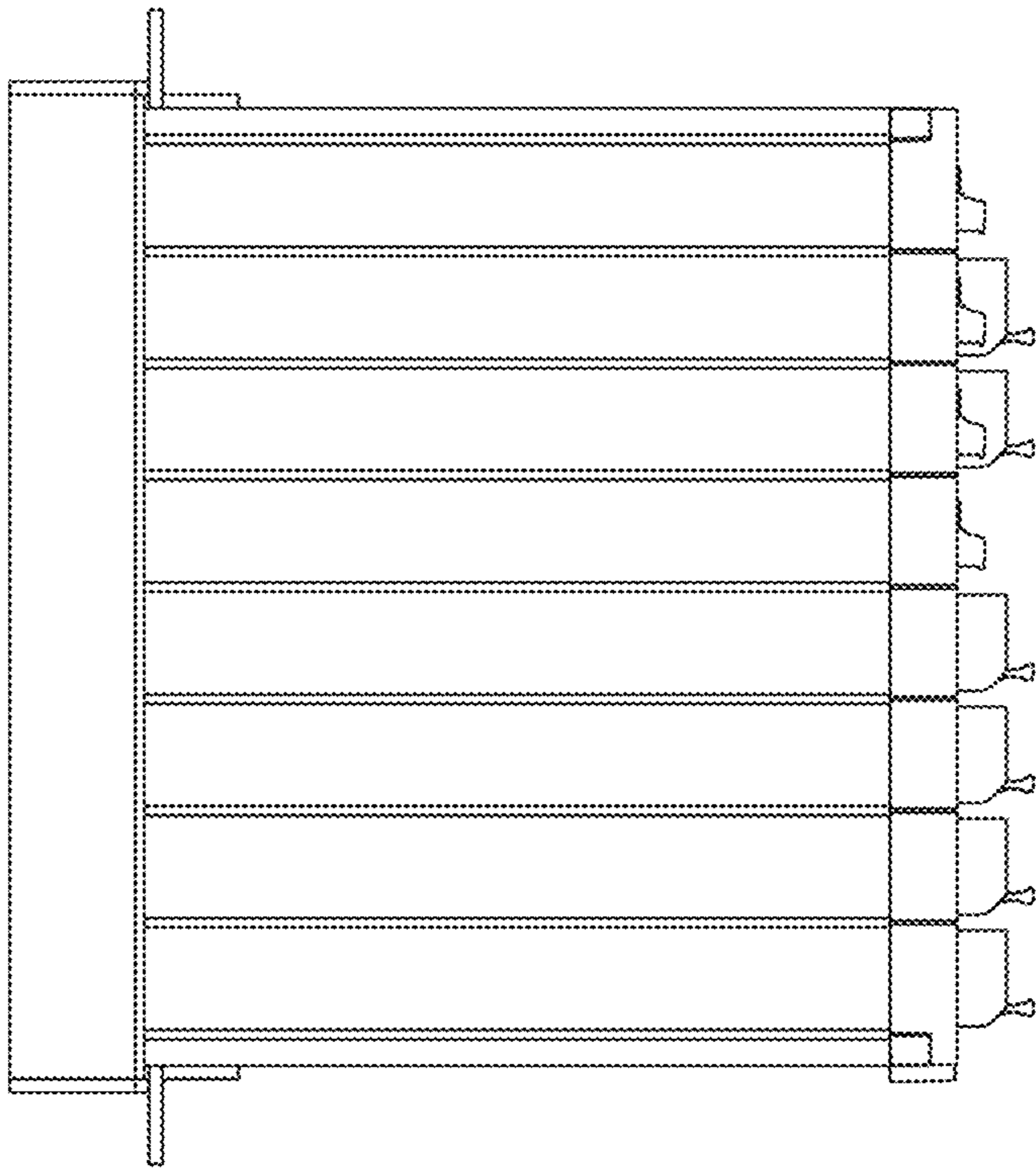


FIG. 6



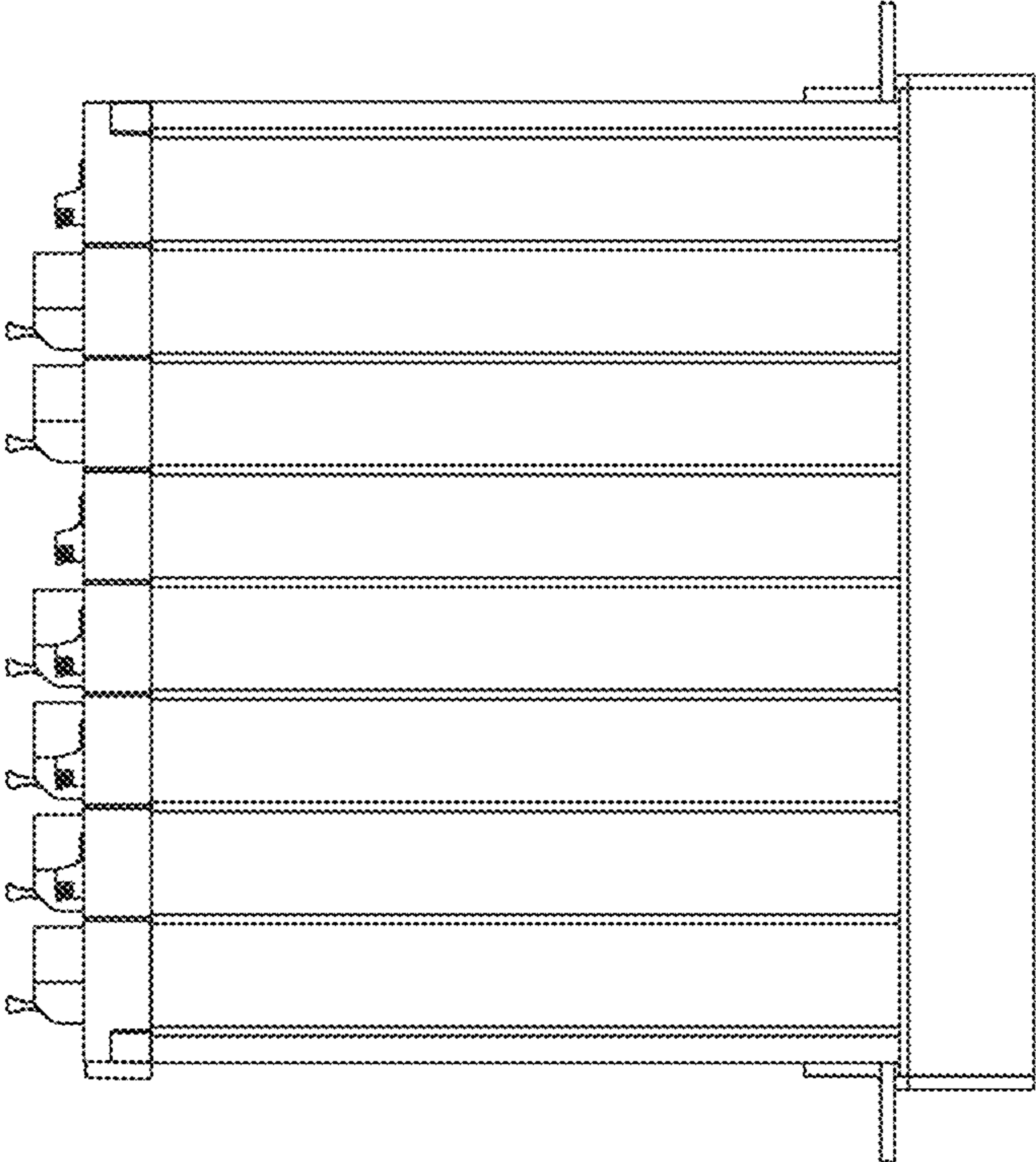


FIG. 7

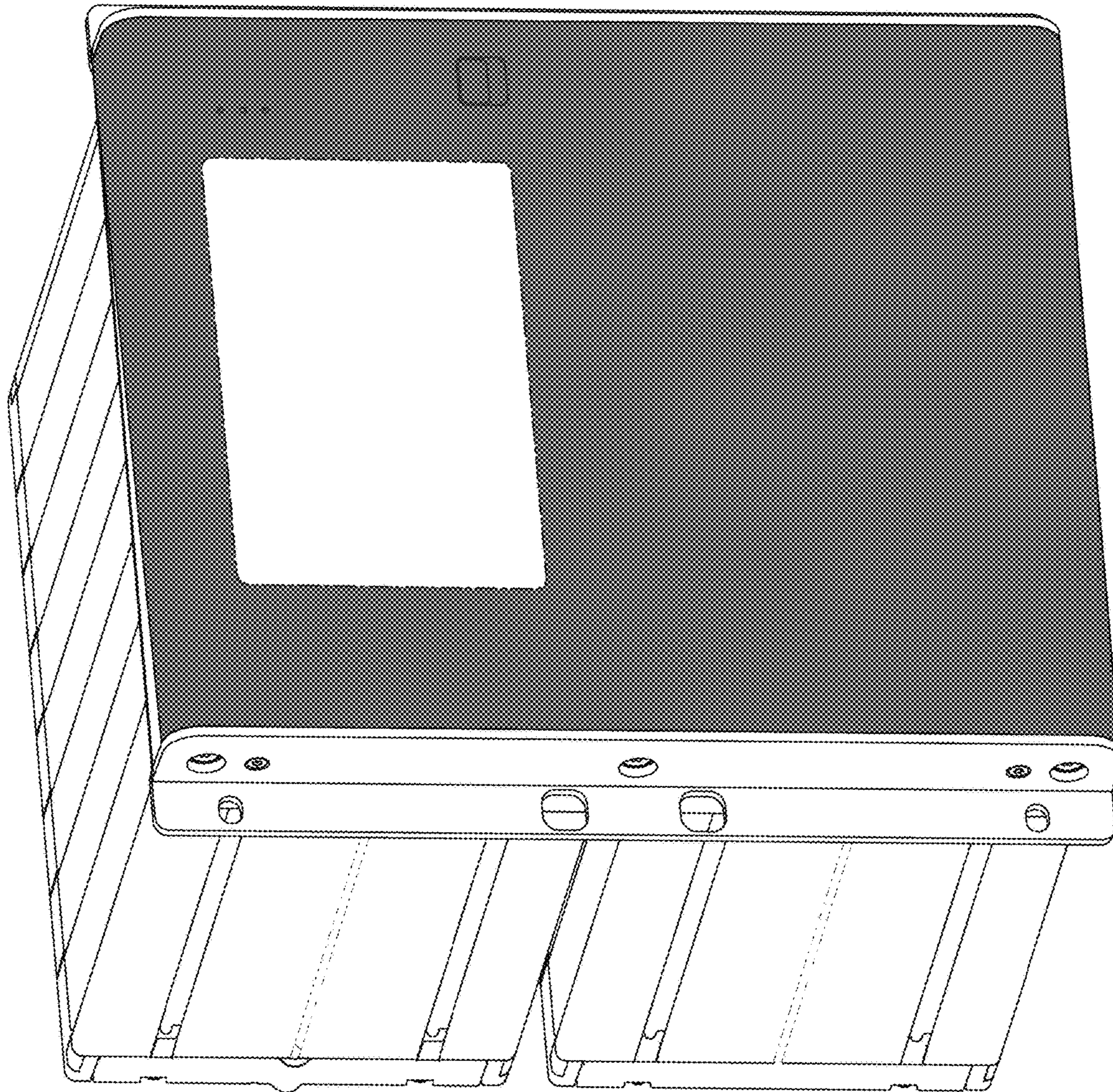


FIG. 8



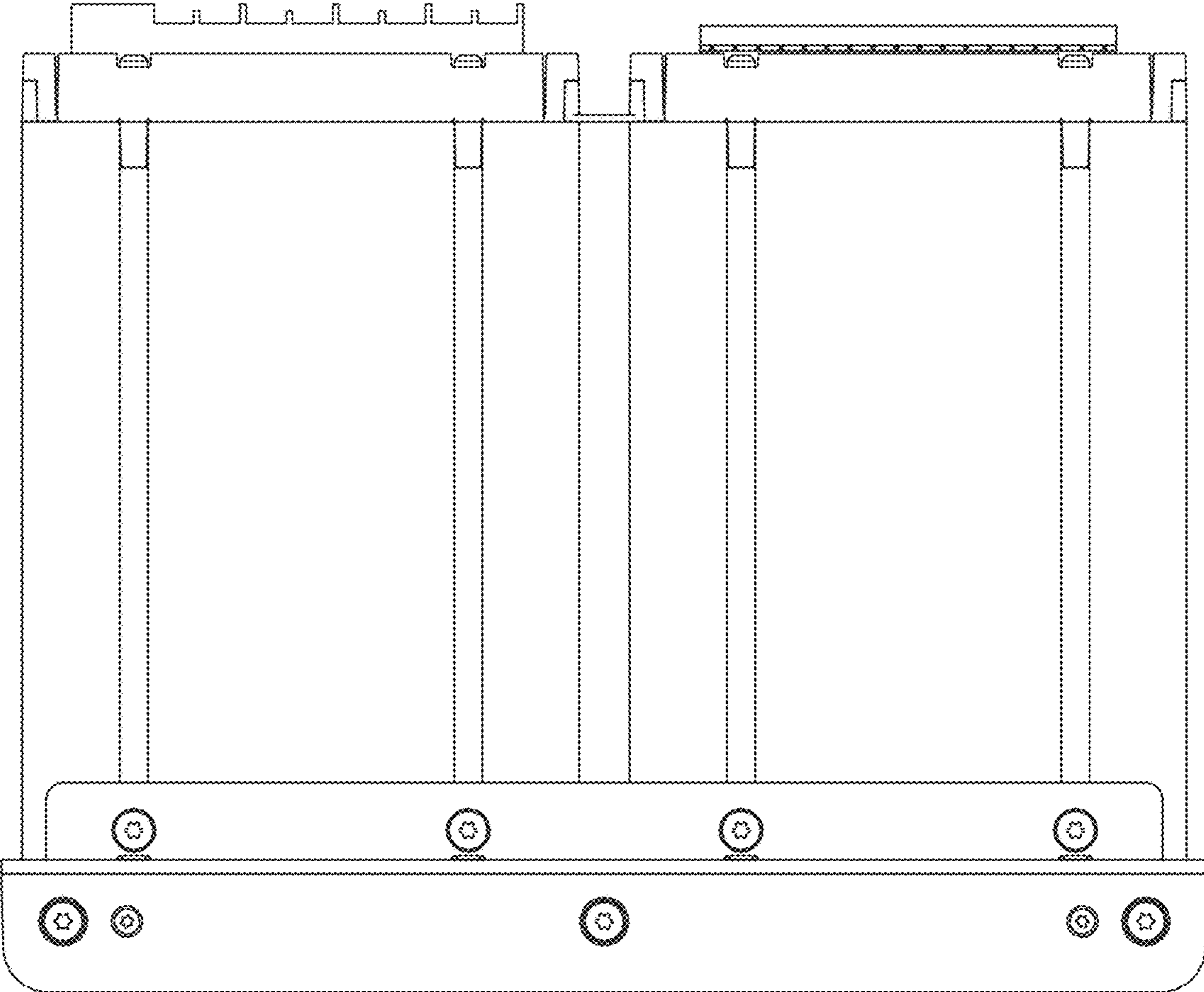


FIG. 9

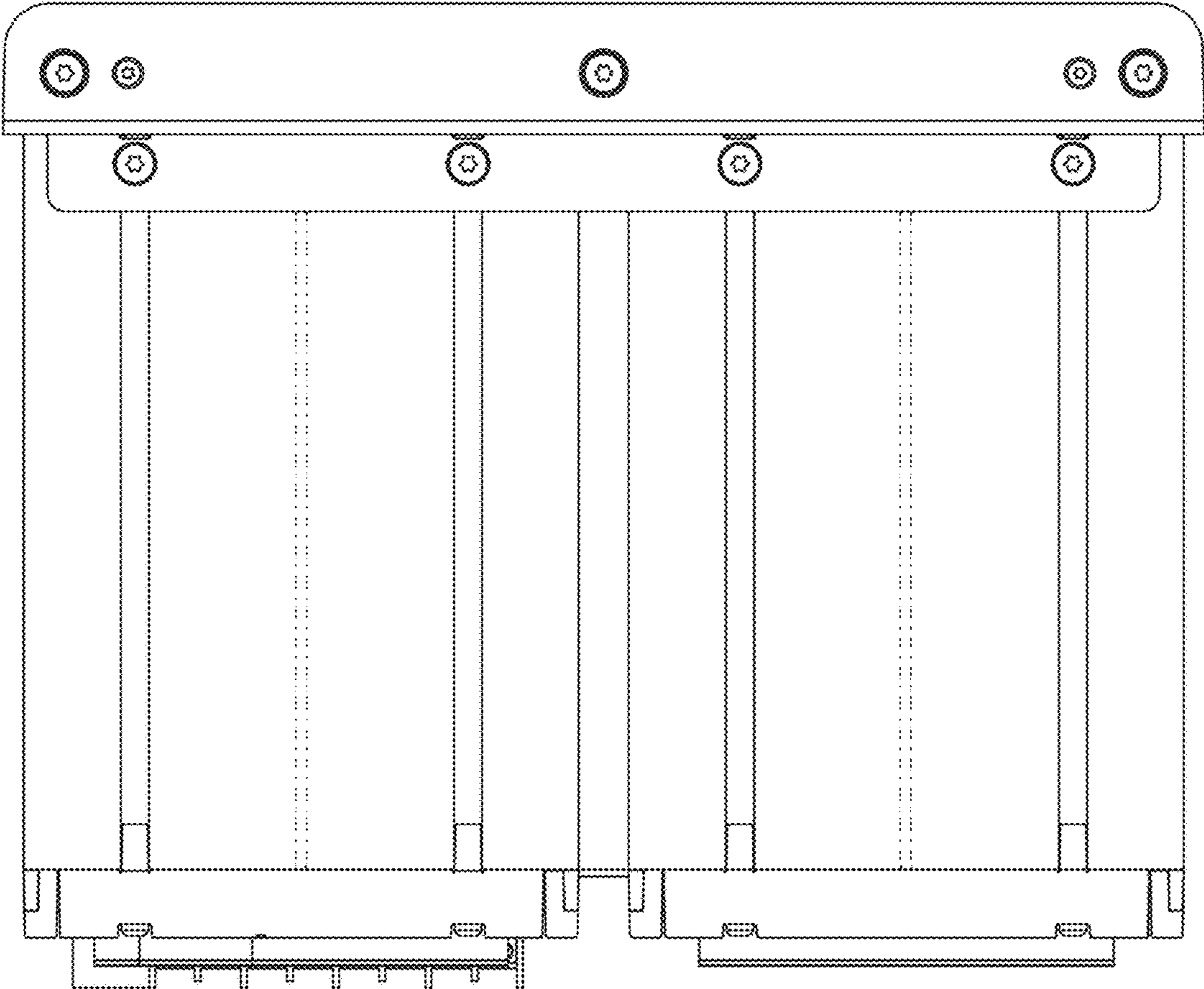


FIG. 10



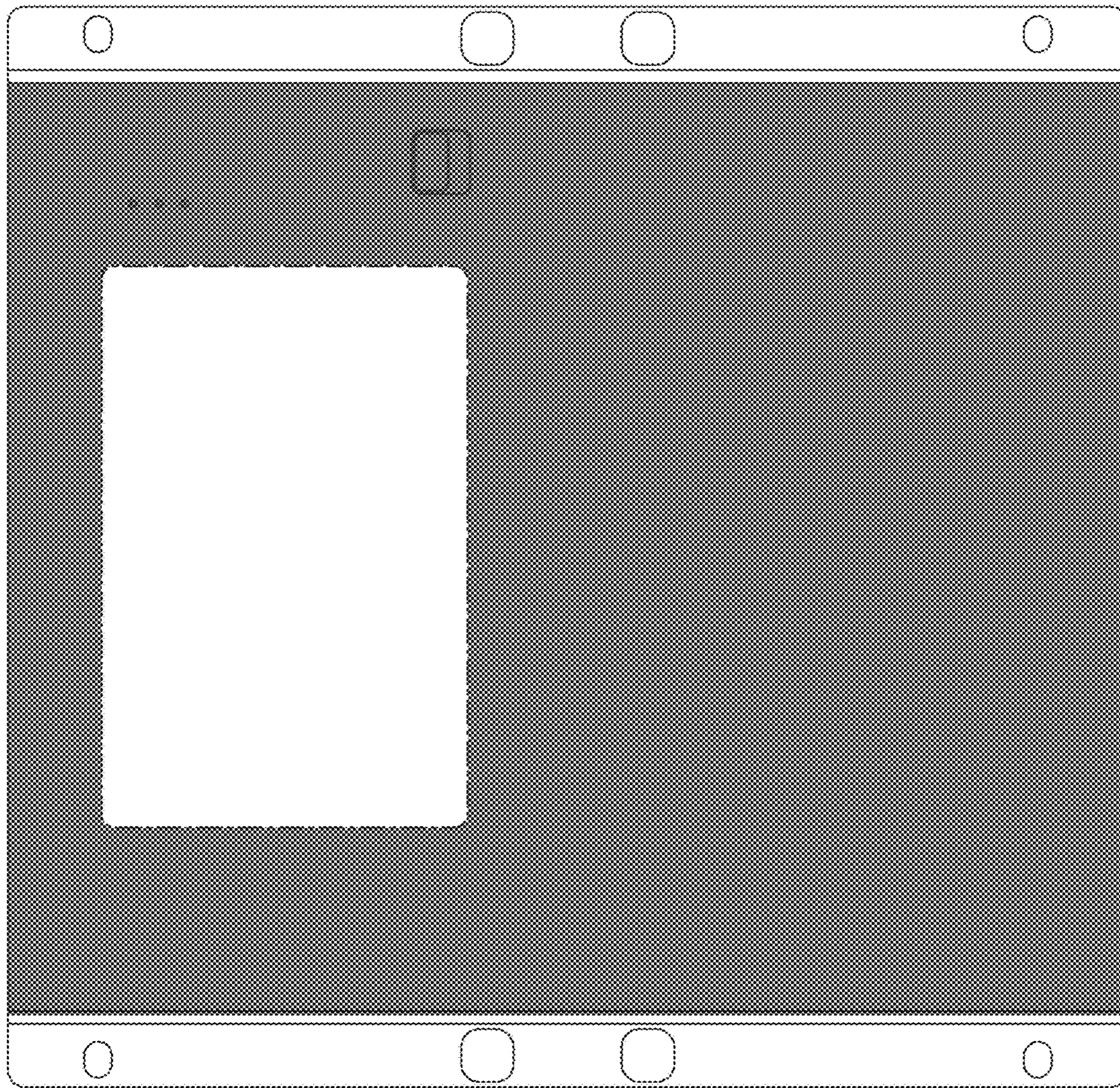


FIG. 11



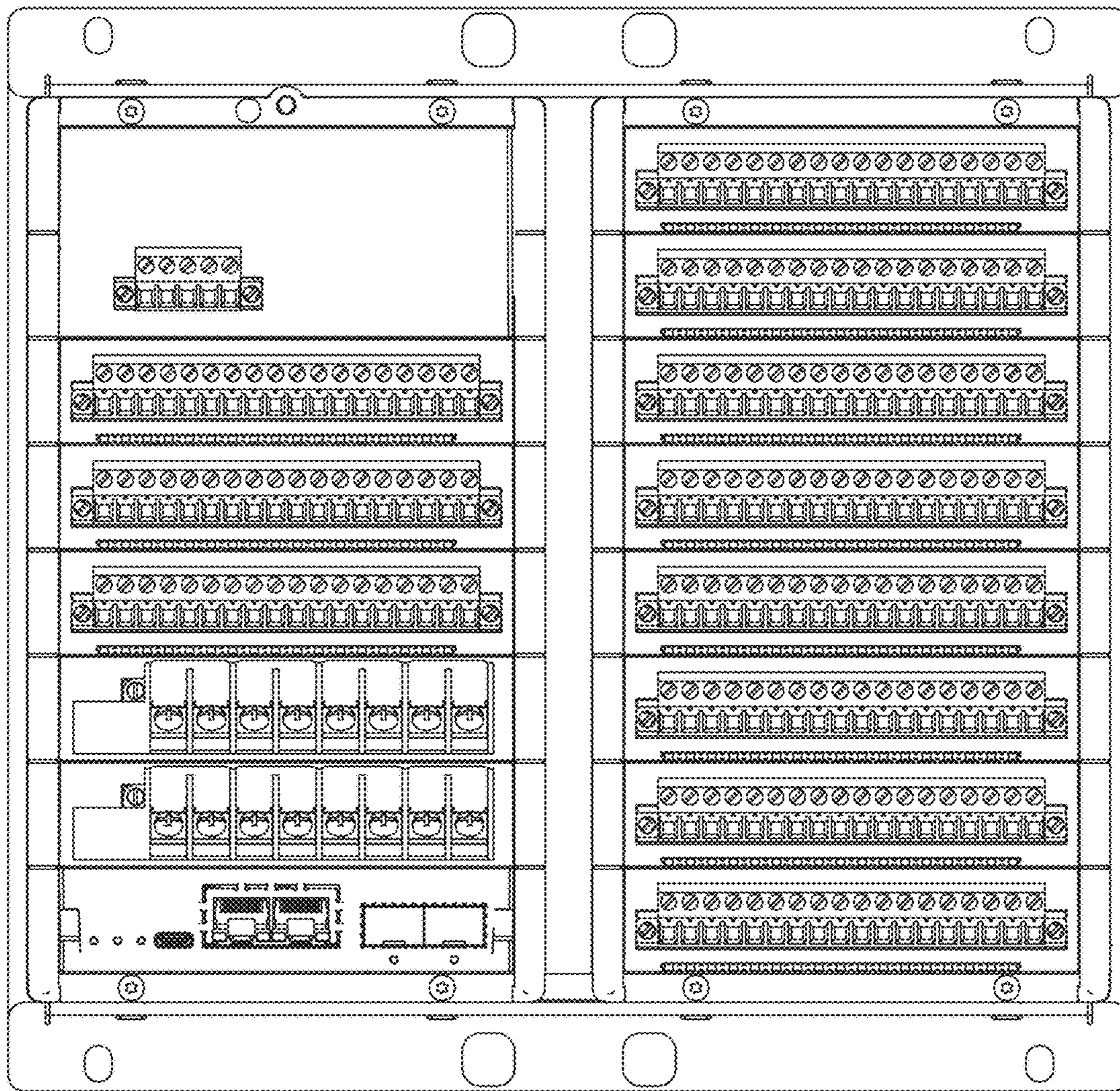


FIG. 12

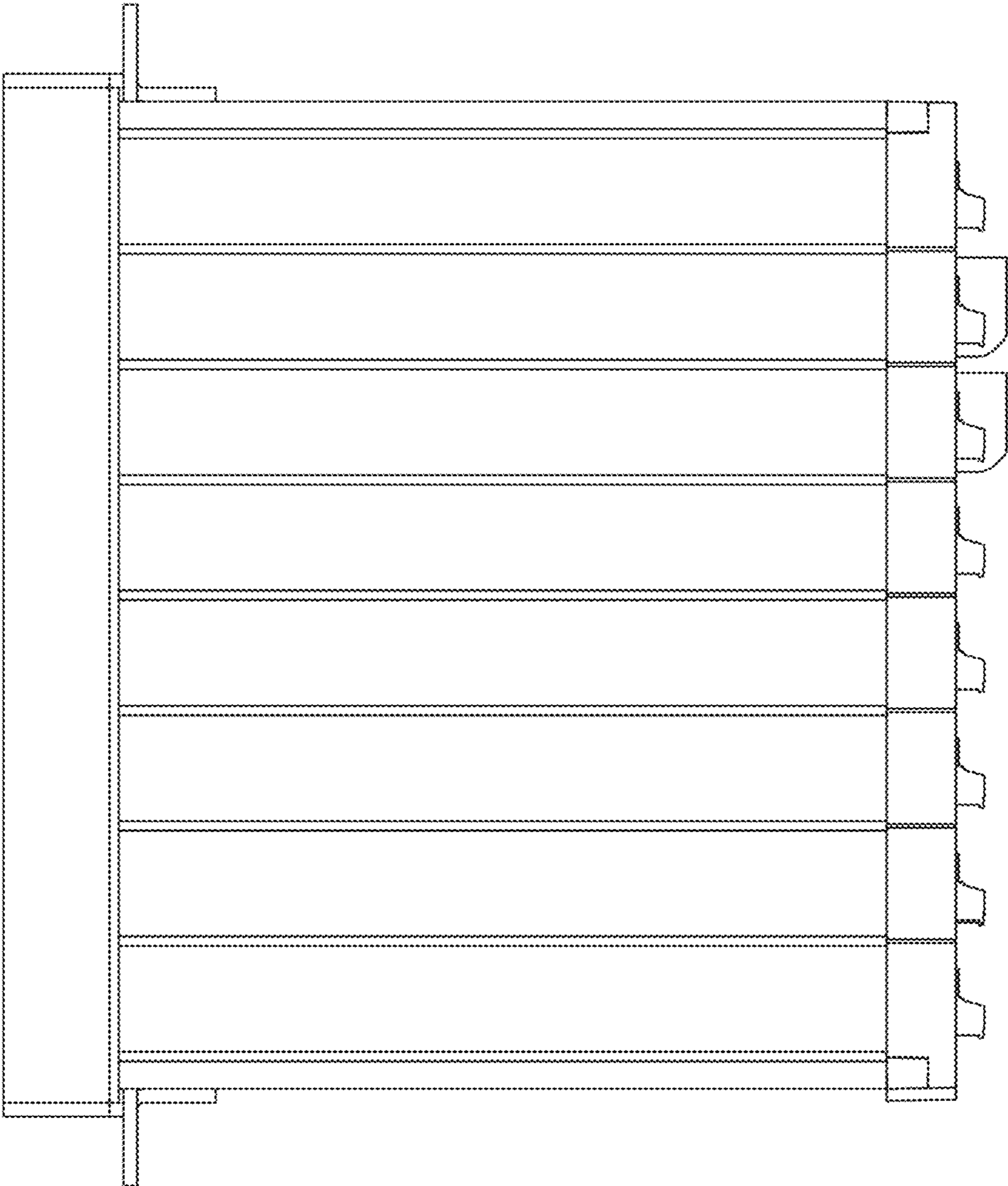


FIG. 13

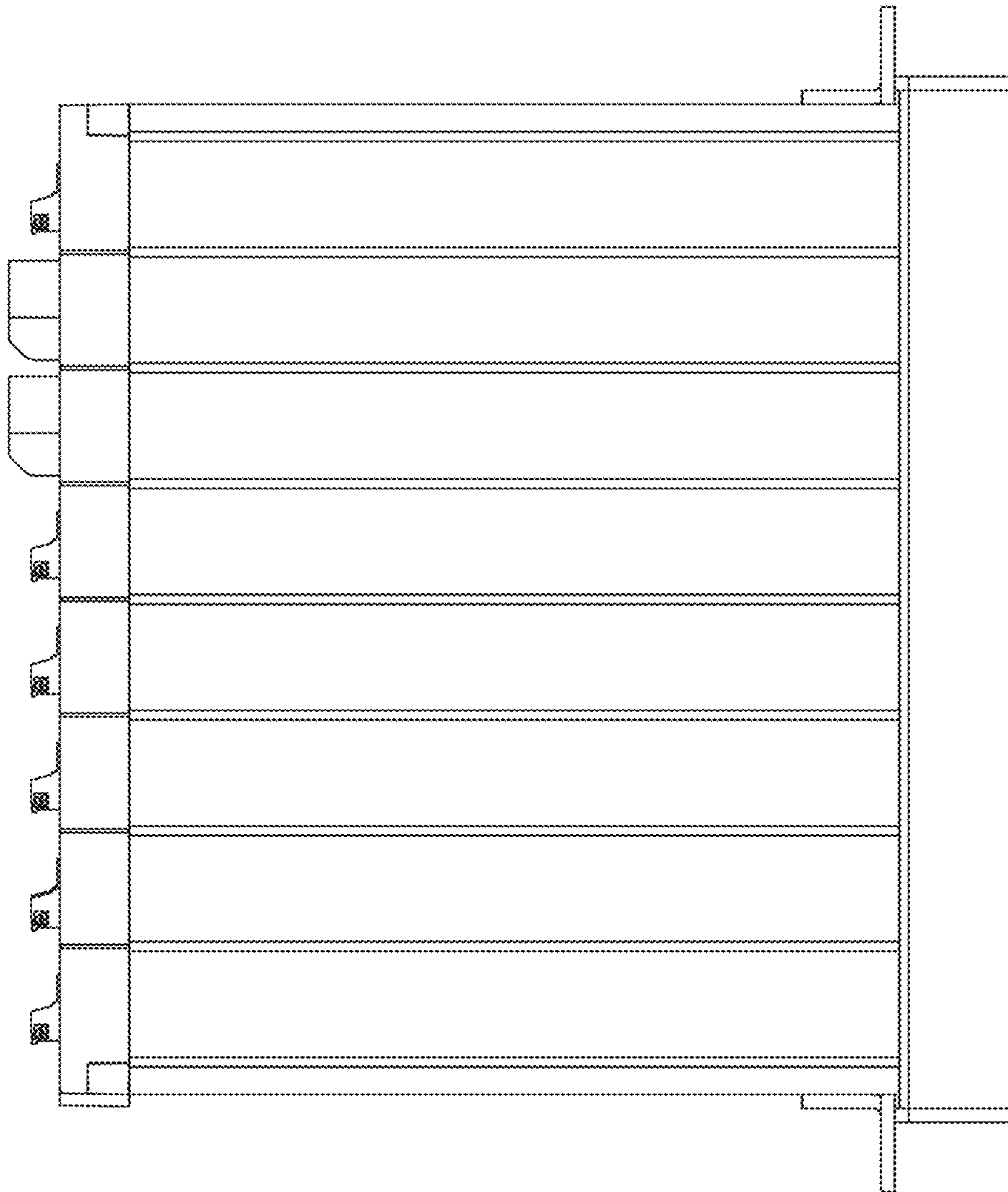


FIG. 14